

The following Listing of Claims will replace all prior versions, and listings, of claims in the application.

LISTING OF CLAIMS:

1. (Currently Amended) An electronic circuit board intermediate member comprising:[:]

a plurality of good interposer ~~board~~ boards; and

a carrier tape being formed an exfoliate layer, ~~and~~

~~wherein~~ the good interposer boards ~~are~~ being disposed on the carrier tape at every predetermined interval, the good interposer board ~~comprising~~ having a base member mounting an IC chip, extended electrodes being formed on the base member and each connected to corresponding electrode of the IC chip.

2. (Currently Amended) A manufacturing method for manufacturing an electronic circuit board intermediate member comprising:[:]

~~a process for~~ applying adhesive on extended electrodes of an interposer board tape, the interposer board tape being obtained by forming the extended electrodes on a base member, a plurality of IC ~~chip~~ chips being mounted on the base member, and each of the extended electrodes being connected to corresponding electrode of each of the IC ~~chip~~ chips;

~~a process for~~ obtaining individual interposer boards by cutting the interposer board tape, ~~a process for~~ and selecting only good interposer boards; and

~~a process for~~ disposing only the interposer boards on a carrier tape at every predetermined interval, the carrier tape being obtained by forming an exfoliate layer on a base tape.

3. (Currently Amended) A manufacturing apparatus for manufacturing an electronic circuit board intermediate member comprising:[]:]

first means for applying adhesive on extended electrodes of an interposer board tape, the interposer board tape being obtained by forming the extended electrodes on a base member, a plurality of IC ~~chip~~ chips being mounted on the base member, and each of the extended electrodes being connected to corresponding electrode of each of the IC ~~chip~~ chips;

second means for obtaining individual interposer boards by cutting the interposer board tape;

third means for selecting only good interposer boards; and

fourth means for disposing only the interposer boards on a carrier tape at every predetermined interval, the carrier tape being obtained by forming an exfoliate layer on one face of a base tape.

4. (Currently Amended) A manufacturing method for manufacturing non-contact ID card and the like comprising:[]:]

peeling an interposer board from an electronic circuit board intermediate member, the electronic circuit board intermediate member being obtained by disposing interposer boards

on a carrier tape at every predetermined interval, the interposer board being obtained by mounting an IC chip, by forming extended electrodes each connected to a corresponding electrode of the IC chip, and by forming an adhesive layer to cover the extended electrodes, the carrier tape being obtained by forming an exfoliate layer on one face of a base tape; and

depressing the interposer board to an antenna circuit board tape ~~so as~~ to face antenna electrodes formed on an antenna circuit base material film and the extended electrodes.

5. (Currently Amended) A manufacturing apparatus for manufacturing non-contact ID card and the like comprising: [[;]]

means for peeling an interposer board one by one from an electronic circuit board intermediate member, the electronic circuit board intermediate member being obtained by disposing interposer boards on a carrier tape at every predetermined interval, ~~the~~ each interposer board being obtained by mounting an IC chip, by forming extended electrodes each connected to corresponding electrode of the IC chip, and by forming an adhesive layer to cover the extended electrodes, the carrier tape being obtained by forming an exfoliate layer on one face of a base tape; and

means for depressing the interposer board to an antenna circuit board tape ~~so as~~ to face antenna electrodes formed on an antenna circuit base material film and the extended electrodes.